

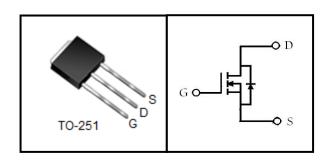
## 200V N-Channel Trench MOSFET

#### **FEATURES**

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Hard switched and high frequency circuits





Device Marking and Package Information				
Device	Package	Marking		
CTU20N170	TO-251	CTU20N170		

Absolute Maximum Ratings at T <sub>j</sub> = 25°C unless otherwise noted					
Parameter		Symbol	Value	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)		$V_{DSS}$	200	٧	
Continuous Drain Current T <sub>C</sub> = 25°C	(note1)	l <sub>D</sub>	18	Α	
Continuous Drain Current T <sub>C</sub> = 100°C	(note1)		12	Α	
Drain Current-Continuous@ Current-Pulsed	(note2)	I <sub>DM</sub>	40	А	
Gate-Source Voltage (VDS=0V)		$V_{GSS}$	±20	٧	
Single Pulse Avalanche Energy	(note3)	E <sub>As</sub>	15	mJ	
Maximum Power Dissipation(Tc=25°C)	(note4)	P <sub>D</sub>	83	W	
Operating Junction and Storage Temperature F	Range	$T_J,T_stg$	-55~+175	°C	

Thermal Characteristics					
Parameter		Symbol	Value	Unit	
Thermal Resistance, Junction-to-Case	(note1)	$R_{ heta JC}$	3.6	°C/W	
Thermal Resistance, Junction-to-Ambient	(note1)	$R_{\theta JA}$	62		



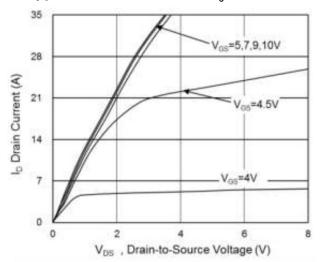
				Value			
Parameter	Symbol	Test Conditions	Value			Unit	
			Min.	Тур.	Max.		
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	200			V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 200V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	uA	
	.022	$V_{DS} = 200V, V_{GS} = 0V, T_{J} = 55^{\circ}C$			5	<u> </u>	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 20V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		2.5	V	
Drain-Source On-Resistance	D	$V_{GS} = 10V, I_{D} = 8A$		140	170	mΩ	
	R <sub>DS(on)</sub>	$V_{GS} = 4.5V, I_{D} = 8A$		150	180	mΩ	
Dynamic							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$		2047		pF	
Output Capacitance	C <sub>oss</sub>			109			
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		70			
Total Gate Charge	$Q_g$			45		nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 80V, I_{D} = 9A, V_{GS} = 10V$		9			
Gate-Drain Charge	$Q_{gd}$	60		10.5			
Turn-on Delay Time	t <sub>d(on)</sub>			13		ns	
Turn-on Rise Time	t <sub>r</sub>	$V_{DS} = 100V, I_{D} = 9A,$		8.2			
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 3\Omega$ , $V_{GS} = 10V$ ,		25			
Turn-off Fall Time	t <sub>f</sub>			11			
<b>Body Diode Characteristics</b>							
Continuous Body Diode Current	Is				18	А	
Pulsed Diode Forward Current	I <sub>SM</sub>				40		
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = 9A$ , $V_{GS} = 0V$			1.2	V	
Reverse Recovery Time	t <sub>rr</sub>	$I_F = 9A$ $di_F/dt = 100A/\mu s$		37		ns	
Reverse Recovery Charge	Q <sub>rr</sub>	TJ=25°C		103		nC	

#### Notes

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width≤300us , duty cycle≤2%
- 3. The EAS data shows Max. rating . The test condition is VDD =25V, VGS =10V, L=0.1 mH  $\,$
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



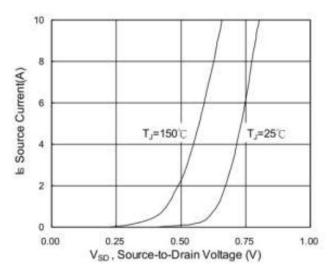
# **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted



180 180 160 140 120 2 4 6 8 10

Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs. G-S Voltage



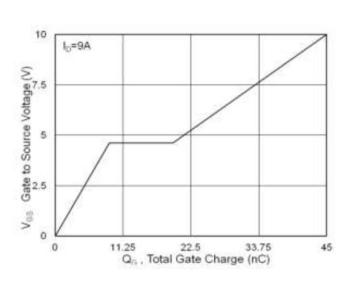
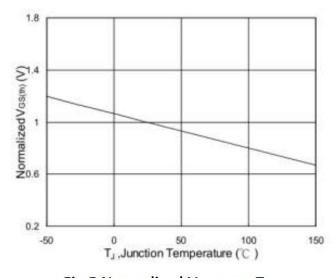


Fig.3 Forward Characteristics of Reverse Diode

Fig.4 Gate-Charge Characteristics



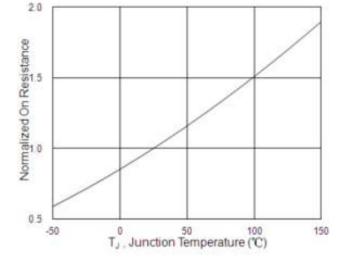
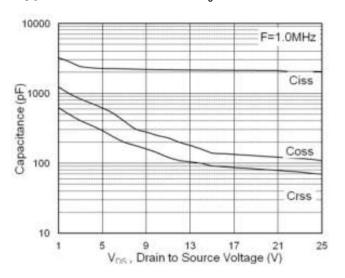


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

Fig. 6 Normalized RDSON vs. TJ



## **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted



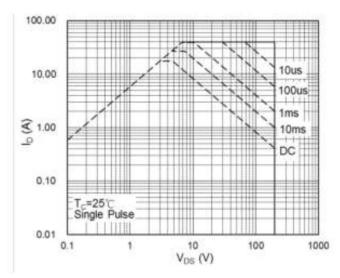


Fig.7 Capacitance

Fig.8 Safe Operating Area

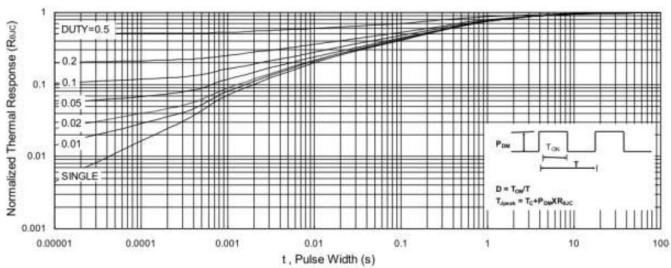


Fig.9 Normalized Maximum Transient Thermal Impedance



Figure A: Gate Charge Test Circuit and Waveform

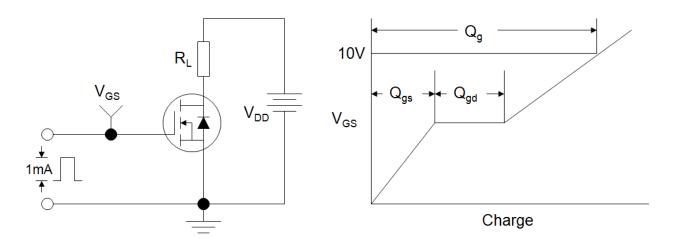


Figure B: Resistive Switching Test Circuit and Waveform

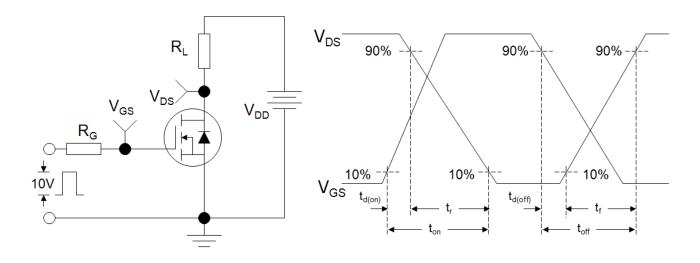
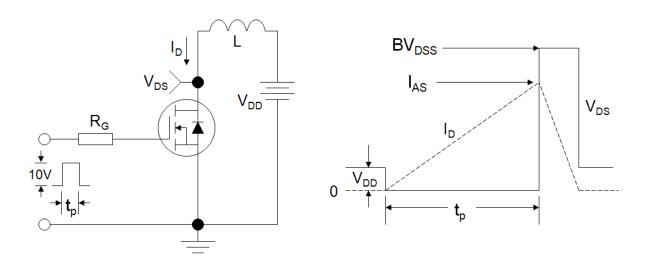
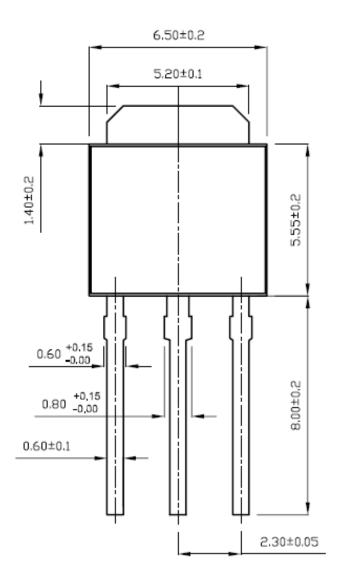


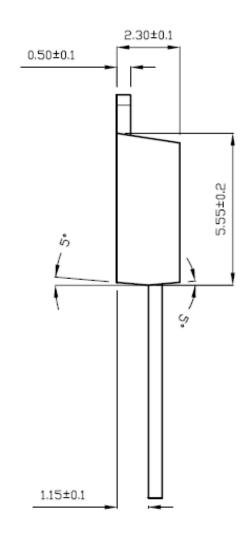
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





# TO-251







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